

Now Available!

THE WORLDWIDE IC PACKAGING MARKET

2012 EDITION

**The Most Comprehensive Report Available
On The Global IC Packaging Industry**

Report Highlights

- **Industry Overview**
 - ◆ Economic Overview
 - ◆ Semiconductor Industry Analysis

- **Worldwide IC Packaging Market Forecasts, 2010–2016**
 - ◆ Units
 - ◆ Package Prices
 - ◆ Packaging Revenue
 - ◆ By Semiconductor Product
 - ◆ By Package Family
 - ◆ By I/O Range

- **Contract IC Packaging Market Forecasts, 2010–2016**
 - ◆ Units
 - ◆ Package Prices
 - ◆ Packaging Revenue
 - ◆ Competitive Rankings
 - ◆ Company Profiles

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The Worldwide IC Packaging Market, 2012 Edition

Synopsis

Following a year of unprecedented growth in 2010 (IC revenue grew 40.6% while units expanded 35.5%), 2011 experienced a slight downturn in the second half of the year. Semiconductor industry growth is expected to expand by only 4% in 2012 but take an upward path thereafter.

Overall the IC market is being driven by demand for handheld consumer devices and the adjoining infrastructure. The automobile industry has recovered, which are laden with semiconductor devices, yet supply has been dampen with the tsunami flooding of Japan and Thailand. The economic uncertainty of Europe and developments in the Arab Spring are other affecting factors.

New Venture Research (NVR), in **The Worldwide IC Packaging Market, 2012 Edition**, analyzes the semiconductor industry and uses this analysis to forecast the future of the global IC packaging market. The report begins with an economic and industry overview, historic and future unit and revenue graphs, and a SATS company overview.

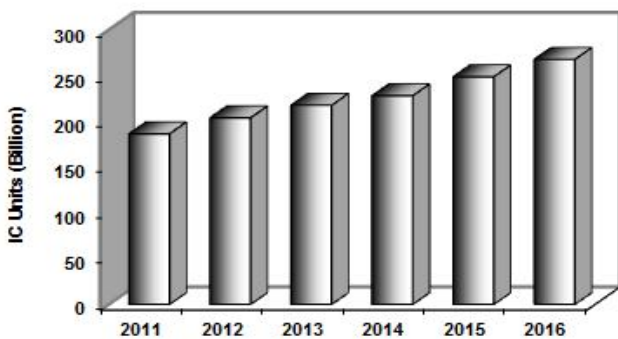


Figure 1 IC Unit Forecast

Following this high-level review, the report presents forecasts for each semiconductor product type, and segments these products by package family and I/O count range. Packaging revenue figures are displayed for each segment, based on prices charged in the contract assembly market. The package families are then rolled up by I/O count and semiconductor product. In doing so, the report generates the total value of the IC packaging industry.

Next, the report presents *NVR's* continuing, extensive coverage of the packaging contractor market. Packaging contractors will continue to assume a larger share of the world's IC packaging business. The report breaks the contractor market down by package families and major product categories providing units and revenue for each category. To help you further assess this group of companies, the report profiles the activities of the world's largest contractors and the packages they offer.

The Worldwide IC Packaging Market, 2012 Edition continues *NVR's* leadership position in assessing the status and future of IC packaging. This report will provide you with an effective and economical tool for assessing the future of this market. The report sells for \$3495 and is delivered by email as a single-user PDF file. Extra single-user licenses sell for \$250 each and a corporate license is \$1000. With the purchase of the report, an Excel spreadsheet of all tables may be obtained for an additional \$500.

About the Author

Sandra Winkler is the senior analyst for IC packaging at New Venture Research (NVR). She began her analyst career as an independent consultant to the telecommunications industry more than 20 years ago. Ms. Winkler has authored widely cited reports on IC packaging since 1995 for Electronic Trend Publications (ETP) which is now NVR. She has spoken at numerous industry conferences and has written articles for a variety of trade publications. Ms. Winkler has an MBA from Santa Clara University.

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DRAM

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SRAM

ROM and EPROM

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Digital Bipolar

Standard Logic

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Display Drivers

Custom Logic

Amplifiers

Interfaces

Voltage Regulators

Data Converters

Custom Analog

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SOT

SO

TSOP

DFN

CC

QFP

QFN

PGA

BGA

FBGA

WLP

DCA

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Anst China

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Millennium Microtech

Naito Densai Kogyo

NANIUM

Nantong Fujitsu

OSE

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Signetics

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SPEL

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